



APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<p>TO:</p> <p>Part No.:</p> <p>Customer's Part No.:</p>	<p>Please return this copy as a certification of your approval</p> <p>Checked & Approved by:</p> <p>Date:</p>

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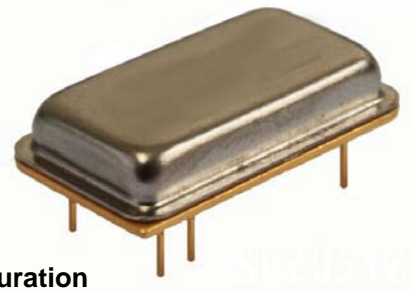


Part No.	:	SDL5111
Pages	:	4
Date	:	2013/6/19
Revision	:	1.0

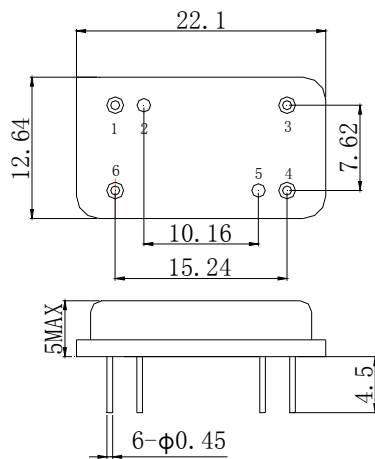
Prepared by:	郑宝琴
Checked by:	
Approved by:	

Features

- RoHS compatible
- Package size 22.1x12.64x5.00mm³
- Package Code DIP2212J
- Electrostatic Sensitive Device(ESD)



Package Dimensions (Unit: mm)



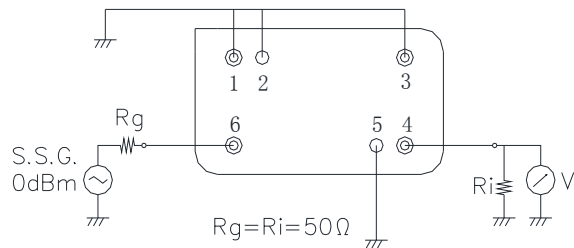
Pin Configuration

Pin No.	Description
6	Input
4	Output
1,2,3,5	Ground

Marking Description

S	Trademark
DL	SAW Delay Line
5111	Part Number
●	Pin 1
YYWW	Year Code & Week Code

Test Circuit



Performance

Maximum Rating

Item		Value	Unit
DC Voltage	V _{DC}	3	V
Operation Temperature	T	-20 ~ +60	°C
Storage Temperature	T _{stg}	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

Electronic Characteristics

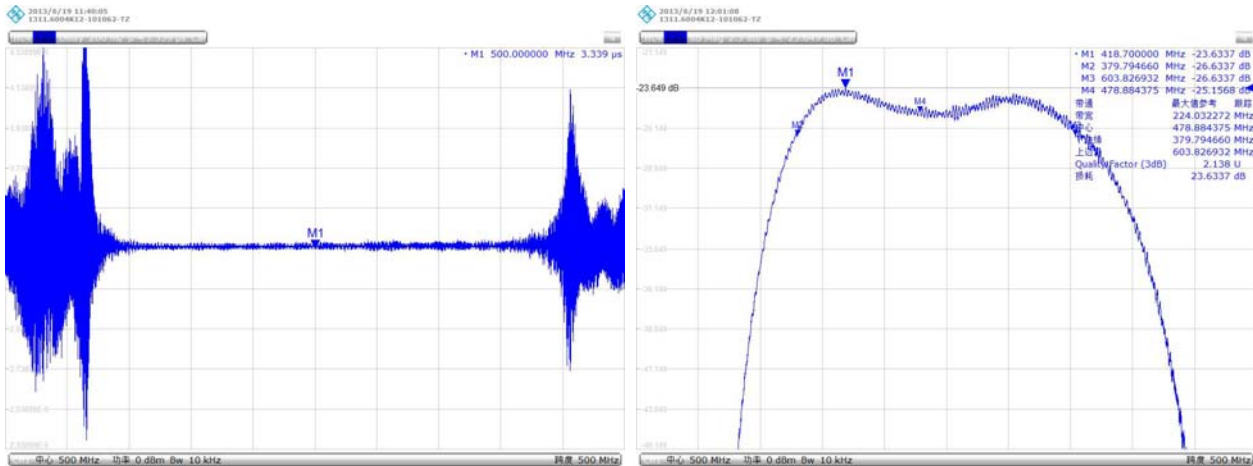
Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		500.0		MHz
Insertion Loss(min)	IL		23.7	30.0	dB
Amplitude Ripple	$\Delta\alpha$		2.5	2.5	dB
3 dB Bandwidth	BW _{3dB}	200.0	224.0		MHz
Absolute Delay	500.00MHz	3.31	3.33	3.35	us

Frequency Characteristics

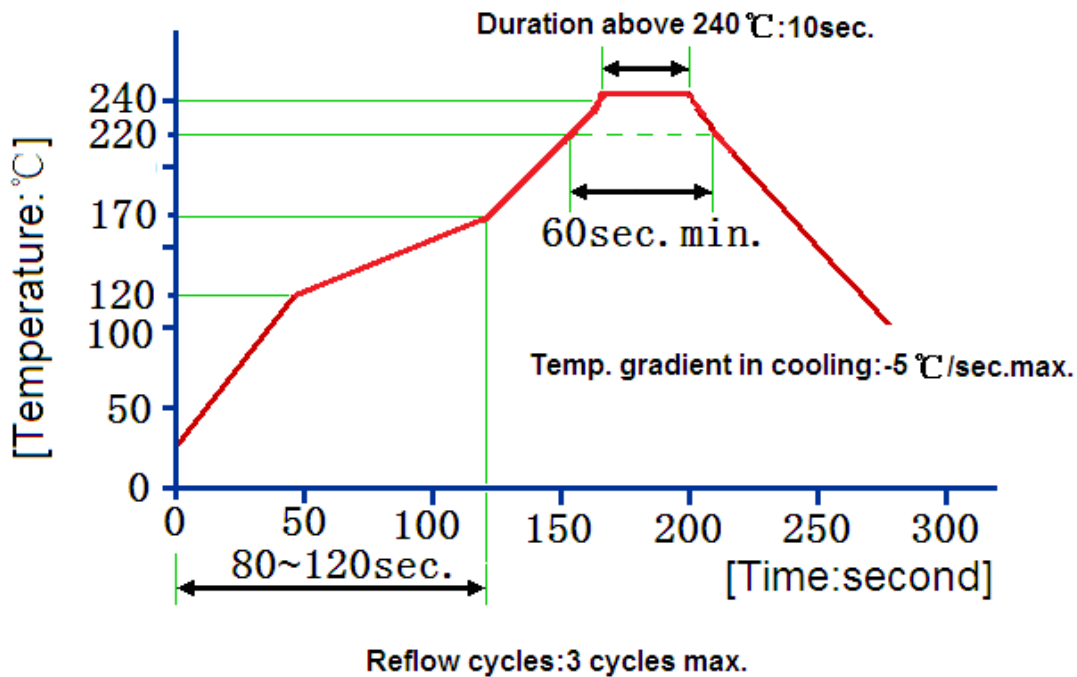


Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h} \pm 0.5\text{h}$ (2) Temperature: $-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h} \pm 0.5\text{h}$
2	Humidity Test	Conditions: $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA= $-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$, TB= $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$, t1=t2=30min, Switch time: $\leq 3\text{min}$, Cycle time: 100 times, Recovery time: $2\text{h} \pm 0.5\text{h}$.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude: 1.5mm Directions: X, Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5

7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2)Temperature of Soldering Iron: 350°C±10°C , Duration: 3~4s , Recovery time : 2 ± 0.5h
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Recommended Reflow Soldering Diagram



Notes

1. As a result of the particularity of inner structure of SAW products, it is easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.